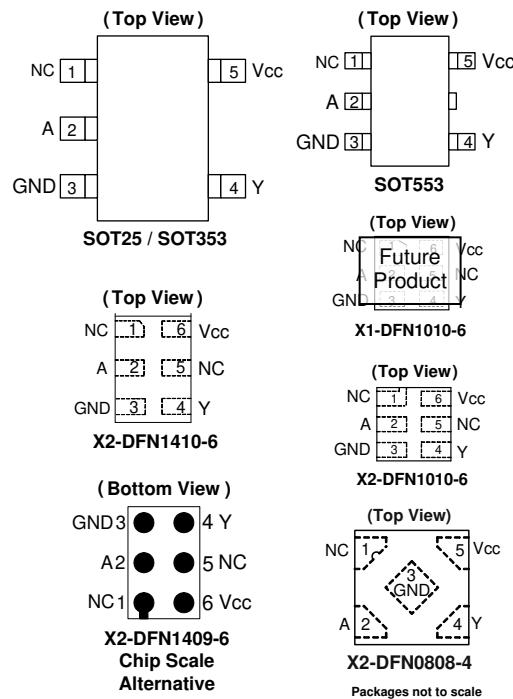


Description

The 74LVC1G14 is a single 1-input Schmitt-trigger inverter with a standard push-pull output. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed-voltage environment. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down. The gate performs the positive Boolean function:

$$Y = \overline{A}$$

Pin Assignments



Packages not to scale

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- $\pm 24\text{mA}$ Output Drive at 3.3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs Accept Up to 5.5V
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115)
 - 2000-V Human Body Model (A114)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)

Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of Products Such as:
 - PCs, Networking, Notebooks, Netbooks, PDAs
 - Computer Peripherals, Hard Drives, CD/DVD ROM
 - TV, DVD, DVR, Set-Top Box
 - Cell Phones, Personal Navigation / GPS
 - MP3 players, Cameras, Video Recorders

Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and < 1000 ppm antimony compounds.

Ordering Information

Logic Device	Function	Package	Packing
74 : Logic Prefix LVC : 1.65 to 5.5 V Logic Family 1G : One Gate	14 : 1-Input Schmitt Trigger Inverter	W5 : SOT25 SE : SOT353 Z : SOT553 FS3 : X2-DFN0808-4 FW5 : X1-DFN1010-6 FW4 : X2-DFN1010-6 FX4 : X2- DFN1409-6 FZ4 : X2- DFN1410-6	-7 : 7" Tape & Reel

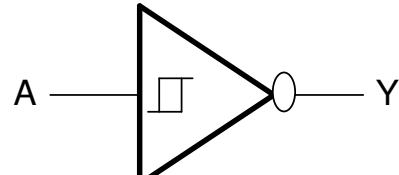
Device	Package Code	Package (Notes 4 & 5)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74LVC1G14W5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm Lead Pitch	3000/Tape & Reel	-7
74LVC1G14SE-7	SE	SOT353	2.0mm × 2.0mm × 1.1mm 0.65mm Lead Pitch	3000/Tape & Reel	-7
74LVC1G14Z-7	SE	SOT553	1.6mm × 1.6 mm × 0.62mm 0.5mm Lead Pitch	4000/Tape & Reel	-7
74LVC1G14FS3-7	FS3	X2-DFN0808-4	0.9mm × 0.9 mm × 0.35mm 0.5mm Pad Pitch (Diamond)	5000/Tape & Reel	-7
74LVC1G14FW5-7 (Future Product)	FW5	X1-DFN1010-6 (Future Product)	1.0mm × 1.0mm × 0.5mm 0.35mm Pad Pitch	5000/Tape & Reel	-7
74LVC1G14FW4-7	FW4	X2-DFN1010-6	1.0mm × 1.0mm × 0.4mm 0.35mm Pad Pitch	5000/Tape & Reel	-7
74LVC1G14FX4-7	FX4	X2-DFN1409-6 (Chip Scale Alternative)	1.4mm × 0.9mm × 0.4mm 0.5mm Pad Pitch	5000/Tape & Reel	-7
74LVC1G14FZ4-7	FZ4	X2-DFN1410-6	1.4mm × 1.0mm × 0.4mm 0.5mm Pad Pitch	5000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes' suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 5. The taping orientation is located on our website at <https://www.diodes.com/assets/Diodes-Packaging/ap02007.pdf>.

Pin Descriptions

Pin Name	Description
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage

Logic Diagram



Function Table

Inputs	Output
A	Y
H	L
L	H

Absolute Maximum Ratings (Notes 6, 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High or Low State	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous Output Current	±50	mA
I _{CC} , I _{GND}	Continuous Current Through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes:

- 6. Stresses beyond the Absolute Maximum Ratings may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range..

Recommended Operating Conditions (Note 8)

Symbol	Parameter		Min	Max	Unit
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data Retention Only	1.5	—	V
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	V _{CC}	V
I _{OH}	High-Level Output Current	V _{CC} = 1.65V	—	-4	mA
		V _{CC} = 2.3V	—	-8	
		V _{CC} = 2.7V	—	-12	
		V _{CC} = 3V	—	-16	
			—	-24	
		V _{CC} = 4.5V	—	-32	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 2.7V	—	12	
		V _{CC} = 3V	—	16	
			—	24	
		V _{CC} = 4.5V	—	32	
T _A	Operating Free-Air Temperature		-40	+125	°C

Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@ $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$. All typical values are at $V_{CC} = 3.3\text{V}$, $T_A = +25^\circ\text{C}$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
V_{T+}	Positive-Going Input Threshold Voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V_{T-}	Negative- Going Input Threshold Voltage	—	1.65V	0.30	—	0.72	—
		—	2.3V	0.58	—	1.00	—
		—	3V	0.80	—	1.30	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.40	—	0.80	—
		—	3V	0.35	—	1.00	—
		—	4.5V	0.55	—	1.10	—
		—	5.5V	0.60	—	1.20	—
V_{OH}	High Level Output Voltage	$I_{OH} = -100\mu\text{A}$	1.65V to 5.5V	$V_{CC} - 0.1$	—	—	V
		$I_{OH} = -4\text{mA}$	1.65V	1.2	—	—	
		$I_{OH} = -8\text{mA}$	2.3V	1.9	—	—	
		$I_{OH} = -12\text{mA}$	2.7V	2.2	—	—	
		$I_{OH} = -16\text{mA}$	3V	2.4	—	—	
		$I_{OH} = -24\text{mA}$		2.3	—	—	
		$I_{OH} = -32\text{mA}$	4.5V	3.8	—	—	
V_{OL}	Low-Level Output Voltage	$I_{OL} = 100\mu\text{A}$	1.65V to 5.5V	—	—	0.1	V
		$I_{OL} = 4\text{mA}$	1.65V	—	—	0.45	
		$I_{OL} = 8\text{mA}$	2.3V	—	—	0.3	
		$I_{OL} = 12\text{mA}$	2.7V	—	—	0.4	
		$I_{OL} = 16\text{mA}$	3V	—	—	0.4	
		$I_{OL} = 24\text{mA}$		—	—	0.55	
		$I_{OL} = 32\text{mA}$	4.5	—	—	0.55	
I_I	Input Current	$V_I = 5.5\text{ V}$ or GND	0 to 5.5V	—	—	± 5	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5\text{V}$	0	—	—	± 10	μA
I_{cc}	Supply Current	$V_I = 5.5\text{V}$ or GND $I_O = 0$	1.65V to 5.5V	—	—	10	μA
ΔI_{cc}	Additional Supply Current	Input at $V_{CC} - 0.6\text{V}$	3V to 5.5V	—	—	500	μA

Electrical Characteristics (continued) (@ $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$. All typical values are at $V_{CC} = 3.3\text{V}$, $T_A = +25^\circ\text{C}$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
V_{T+}	Positive- Going Input Threshold Voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V_{T-}	Negative- Going Input Threshold Voltage	—	1.65V	0.30	—	0.75	—
		—	2.3V	0.58	—	1.03	—
		—	3V	0.80	—	1.33	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.37	—	0.80	—
		—	3V	0.32	—	1.00	—
		—	4.5V	0.50	—	1.20	—
		—	5.5V	0.55	—	1.40	—
V_{OH}	High Level Output Voltage	$I_{OH} = -100\mu\text{A}$	1.65V to 5.5V	$V_{CC} - 0.1$	—	—	V
		$I_{OH} = -4\text{mA}$	1.65V	0.95	—	—	
		$I_{OH} = -8\text{mA}$	2.3V	1.7	—	—	
		$I_{OH} = -12\text{mA}$	2.7V	1.9	—	—	
		$I_{OH} = -16\text{mA}$	3V	1.9	—	—	
		$I_{OH} = -24\text{mA}$		2.0	—	—	
		$I_{OH} = -32\text{mA}$	4.5V	3.4	—	—	
V_{OL}	Low-Level Output Voltage	$I_{OL} = 100\mu\text{A}$	1.65V to 5.5V	—	—	0.1	V
		$I_{OL} = 4\text{mA}$	1.65V	—	—	0.7	
		$I_{OL} = 8\text{mA}$	2.3V	—	—	0.45	
		$I_{OL} = 12\text{mA}$	2.7V	—	—	0.6	
		$I_{OL} = 16\text{mA}$	3V	—	—	0.6	
		$I_{OL} = 24\text{mA}$		—	—	0.8	
		$I_{OL} = 32\text{mA}$	4.5V	—	—	0.8	
I_I	Input Current	$V_I = 5.5\text{V}$ or GND	0 to 5.5V	—	—	± 100	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5\text{V}$	0	—	—	± 200	μA
I_{CC}	Supply Current	$V_I = 5.5\text{V}$ or GND $I_O = 0$	1.65V to 5.5V	—	—	200	μA
ΔI_{CC}	Additional Supply Current	Input at $V_{CC} - 0.6\text{V}$	3V to 5.5V	—	—	5000	μA

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 9)	—	204	—	°C/W
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 9)	—	52	—	°C/W
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 9. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^\circ C$ to $+85^\circ C$, $C_L = 15pF$ as noted (see Figure 1)

Parameter	From Input	To Output	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 5V \pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	9.9	0.7	5.5	0.7	4.6	0.7	4.4	ns

$T_A = -40^\circ C$ to $+85^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 2)

Parameter	From Input	To Output	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 5V \pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	11	0.7	6.5	0.7	5.5	0.7	5	ns

$T_A = -40^\circ C$ to $+125^\circ C$, $C_L = 15pF$ as noted (See Figure 1)

Parameter	From Input	To Output	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 5V \pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	12.5	0.7	7.5	0.7	6.5	0.7	5.5	ns

$T_A = -40^\circ C$ to $+125^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 2)

Parameter	From Input	To Output	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 5V \pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	14.0	0.7	8.5	0.7	7.0	0.7	6.5	ns

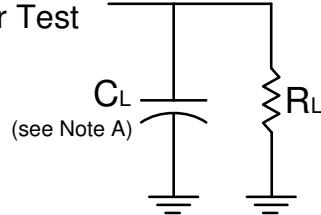
Operating Characteristics

$T_A = +25^\circ\text{C}$

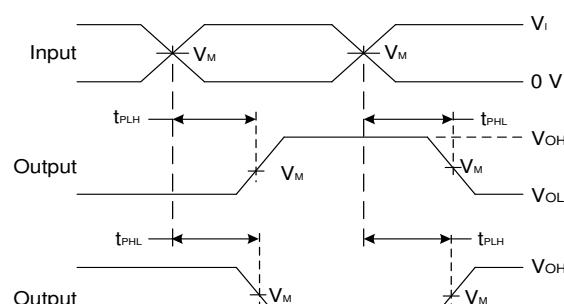
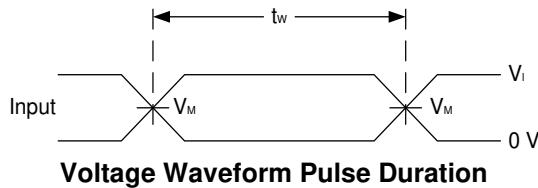
Parameter	Test Conditions	$V_{CC} = 1.8\text{V}$	$V_{CC} = 2.5\text{V}$	$V_{CC} = 3.3\text{V}$	$V_{CC} = 5\text{V}$	Unit
		Typ.	Typ.	Typ.	Typ.	
C_{PD}	Power Dissipation Capacitance $f = 10 \text{ MHz}$	20	21	22	25	pF

Parameter Measurement Information

From Output
Under Test



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
$1.8V \pm 0.15V$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	15pF	$1\text{M}\Omega$
$2.5V \pm 0.2V$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	15pF	$1\text{M}\Omega$
$3.3V \pm 0.3V$	3V	$\leq 2.5\text{ns}$	1.5V	15pF	$1\text{M}\Omega$
$5V \pm 0.5V$	V_{CC}	$\leq 2.5\text{ns}$	$V_{CC}/2$	15pF	$1\text{M}\Omega$



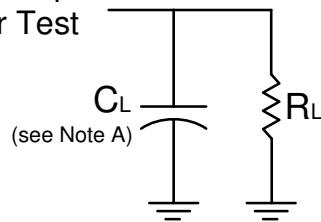
Inverting and Non Inverting Outputs

Figure 1. Load Circuit and Voltage Waveforms

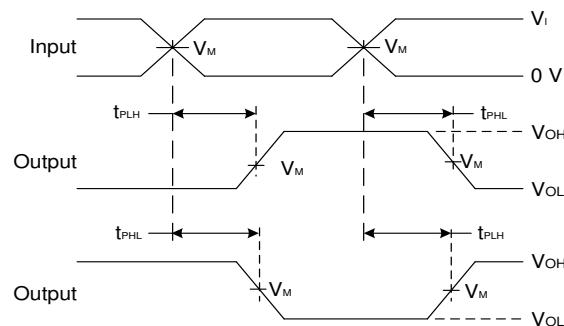
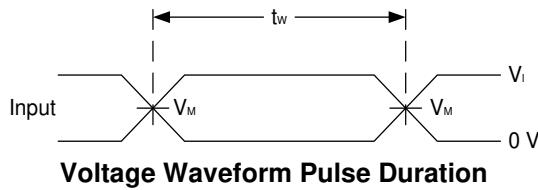
Notes:

- A. Includes test lead and test apparatus capacitance.
- B. All pulses are supplied at pulse repetition rate $\leq 10\text{MHz}$.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Parameter Measurement Information (continued)

 From Output
 Under Test


V _{CC}	Inputs		V _M	C _L	R _L
	V _I	t _r /t _f			
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1kΩ
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω

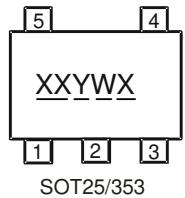

Figure 2. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}.

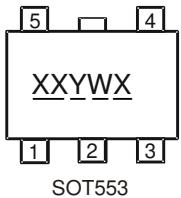
Marking Information

(1) SOT25, SOT353, and SOT553

(Top Views)



SOT25/353



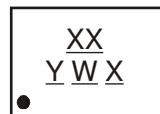
SOT553

XX : Identification Code
 Y : Year 0~9
 W : Week : A~Z : 1~26 week;
 a~z : 27~52 week;
 z represents 52 and 53 week
 X : A~Z : Internal Code

Part Number	Package	Identification Code
74LVC1G14W5-7	SOT25	UP
74LVC1G14SE-7	SOT353	UP
74LVC1G14Z-7	SOT553	UP

(2) DFN Packages

(Top View)



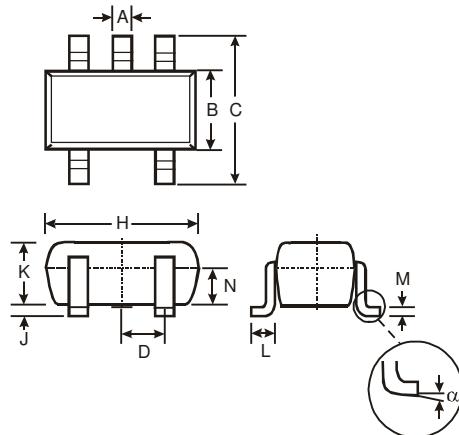
XX : Identification Code
 Y : Year 0~9
 W : Week : A~Z : 1~26 week;
 a~z : 27~52 week;
 z represents 52 and 53 week
 X : A~Z : Internal Code

Part Number	Package	Identification Code
74LVC1G14FS3-7	X2-DFN0808-4	WP
74LVC1G14FW5-7	X1-DFN1010-6	V8
74LVC1G14FW4-7	X2-DFN1010-6	UP
74LVC1G14FX4-7	X2-DFN1409-6	MG
74LVC1G14FZ4-7	X2-DFN1410-6	UP

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

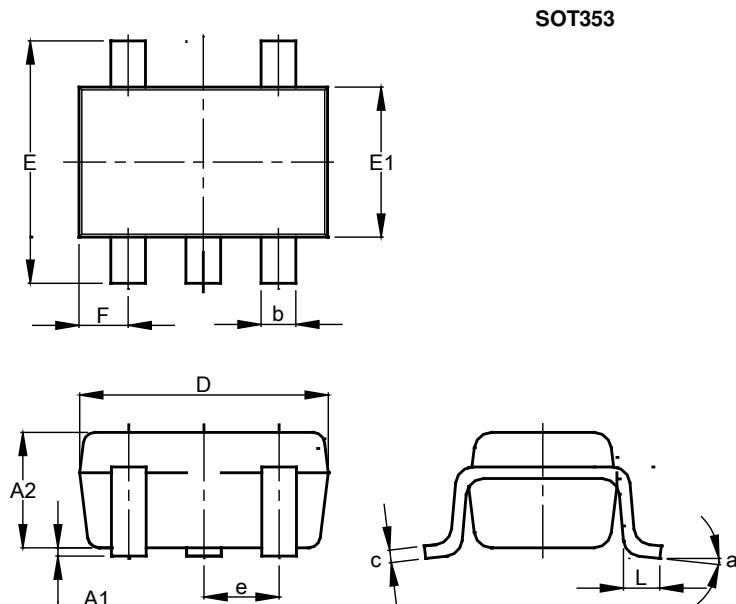
(1) Package Type: SOT25



SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
a	0°	8°	—

All Dimensions in mm

(2) Package Type: SOT353



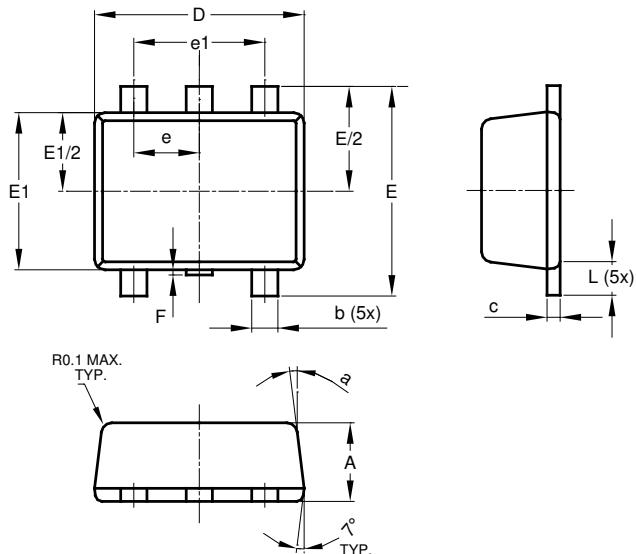
SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	—

All Dimensions in mm

Package Outline Dimensions (continued)

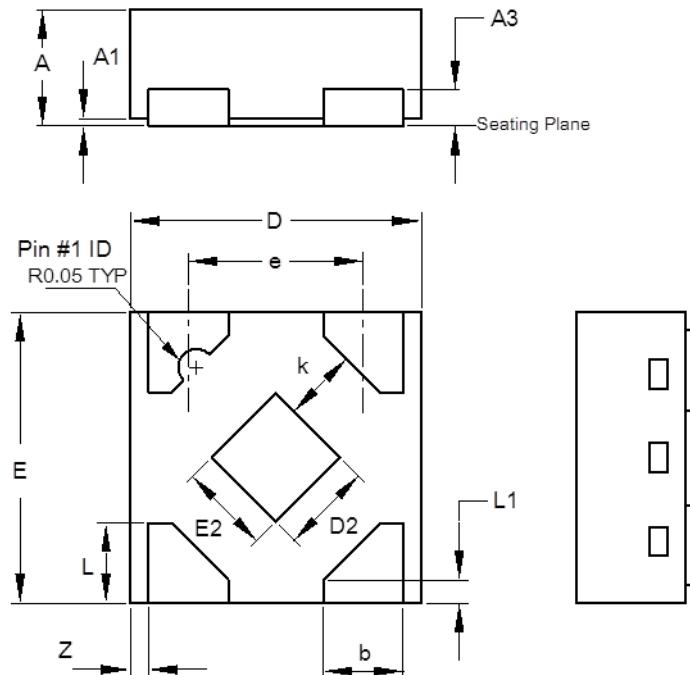
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(3) Package Type: SOT553



SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50	BSC	
e1	1.00	BSC	
F	0.00	0.10	—
L	0.10	0.30	0.20
a	6°	8°	7°
All Dimensions in mm			

(4) Package Type X2-DFN0808-4



X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			

Package Outline Dimensions (continued)

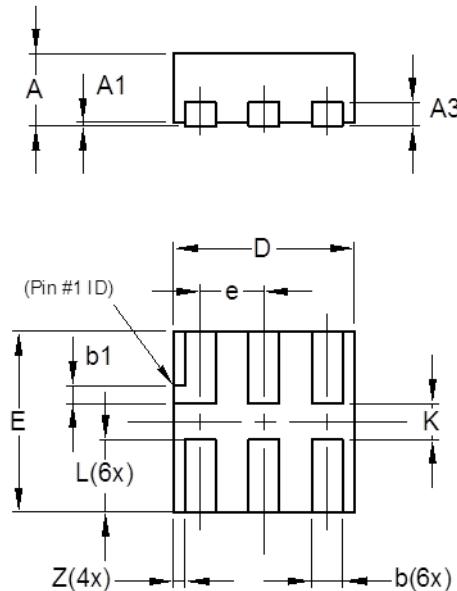
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(5) Package Type: X1-DFN1010-6

(Future Product)

(6) Package Type X2-DFN1010-6

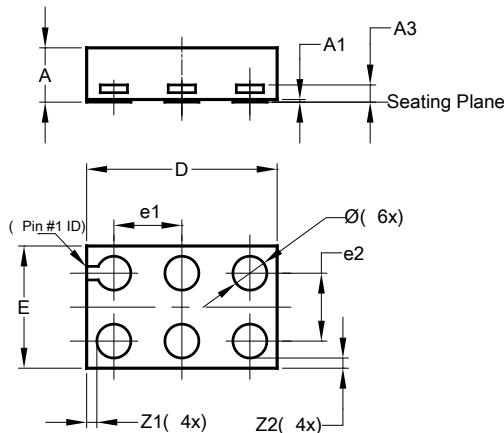
X2-DFN1010-6



X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065

All Dimensions in mm

(7) Package Type: X2-DFN1409-6



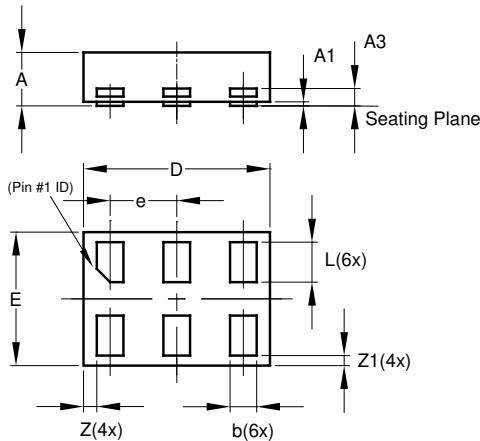
X2-DFN1409-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0	0.05	0.02
A3	—	—	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	—	—	0.50
e2	—	—	0.50
Z1	—	—	0.075
Z2	—	—	0.075

All Dimensions in mm

Package Outline Dimensions (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(8) Package Type: X2-DFN1410-6



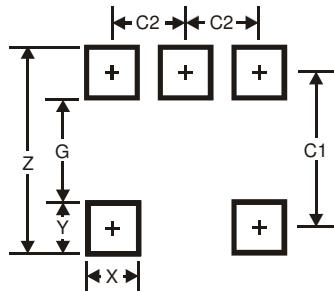
X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075

All Dimensions in mm

Suggested Pad Layout

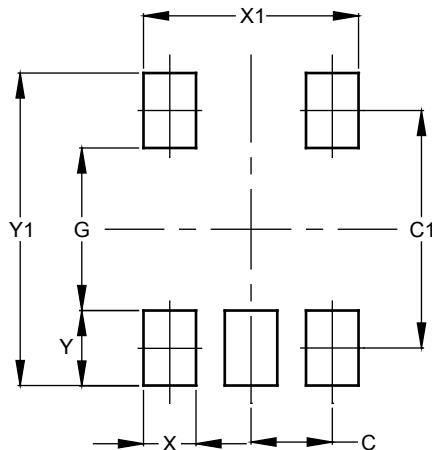
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SOT25



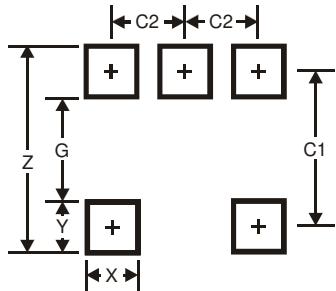
Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: SOT353



Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

(3) Package Type: SOT553

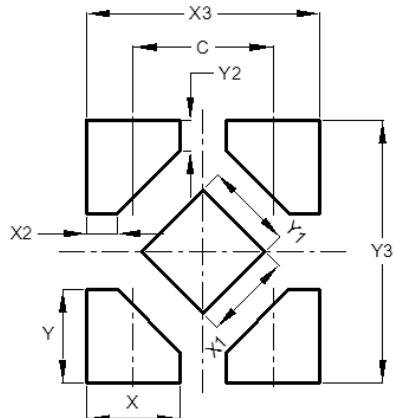


Dimensions	Value
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

Suggested Pad Layout (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4) Package Type X2-DFN0808-4

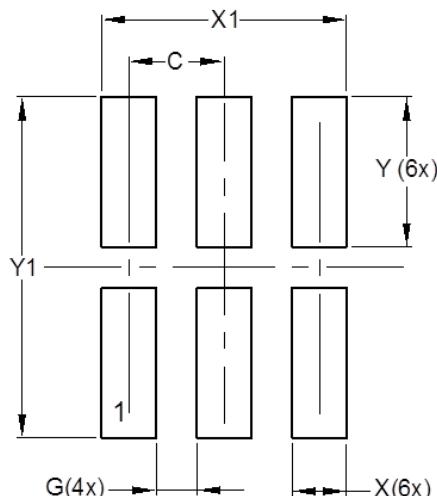


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

(5) Package Type X1-DFN1010-6

(Future Product)

(6) Package Type X2-DFN1010-6

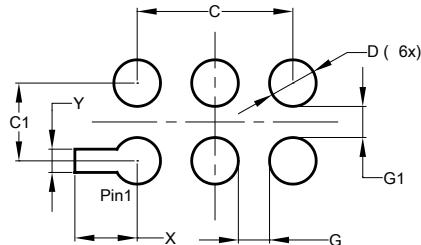


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Suggested Pad Layout (continued)

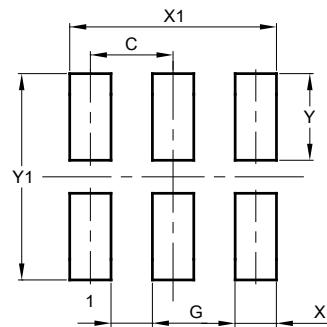
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(7) Package Type: X2-DFN1409-6



Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

(8) Package Type: X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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